

AMENDMENTS TO THE SPECIFICATION

At page 2, line 28 to end of page, please change the paragraph to read:

Such object is substantially achieved through the tool for handling wafers having the features set out in claim 1, of the present invention.

According to a further aspect, the present invention relates also to a station for epitaxial growth treatments, ~~having the features set out in independent claim 9~~, wherein such tool finds an advantageous application.

At page 9, line 21-24, please change the paragraph to read:

In this case, if variable suction is desired, suction system 3 may advantageously comprise a Mass Flow Controller [MFC] 99 programmable, for example, by a computer sending “set points”; such controller controls the flow of inert gas and, as a consequence, the generated pressure depression.